

Reliability Testing of Electronic Components: State-of-the-art and New Trends

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Abstract

In the last years, the methods for testing the reliability of electronic components have evolved significantly, according to the evolution of the technologies for fabricating the components. Accelerated tests, proposed many years ago, became the usual solution, the new trend being towards the use of failure analysis as compulsory step in the procedure for reliability assessment. The paper is reviewing the modern solutions in the reliability testing of electronic components, both for quantitative and qualitative life tests.

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